

### **Features**

Planar die construction.

200mW power dissipation on ceramic PBC.

General purpose, medium current.

Ideally suited for automated assembly processes.

Available in lead free version.



**SOD-123** 

# **Package Marking and Ordering Information**

Product ID		Pack	Marking	Qty(PCS)		
Н	IBZT52C6V27F	SOD-123	WA	3000		



# Absolute Maximum Ratings(Ta=25℃)

Symbol	Parameter	Value	Unit
V <sub>F</sub>	Forward Voltage (Note 2) @ I <sub>F</sub> =10mA	0.9	V
P <sub>d</sub>	Power Dissipationn (Note 1)	500	mW
R <sub>OJA</sub>	Thermal Resistance From Junction To Ambient	625	°C/W
TJ	Operation Junction Temperature Range	-40~+125	$^{\circ}$
T <sub>STG</sub>	Storage Temperature Range	-55~+150	$^{\circ}$ C

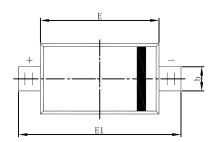
## Electrical Characteristics (Ta=25°C unless otherwise specified)

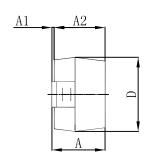
electrical characteristics (1a 20 c amous chief vice opening)												
Туре	Zener Voltage Range (Note 2)			Maximum Zener Impedance (Note 3)		Maximum Reverse Current (Note 2)		Typical Temperature Coefficient		Current		
	V	z @I <sub>ZT</sub>	(V)	I <sub>ZT</sub>	Vz@IzT	Vz@Izĸ	$I_{ZK}$	I <sub>R</sub>	$V_{R}$	/ <sub>R</sub> @I <sub>ZTC</sub> mV/°C		
	Nom	Min	Max	(mA)	2	Ω	(mA)	μΑ	٧	Min	Max	mA
HBZT52C6V27F	6.2	5.89	6.51	5	5.7	9.5	1.0	2.4	4	0.4	3.7	5

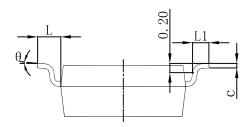
#### Notes:

- 1. Device mounted on ceramic PCB: 7.6mm x 9.4mm x 0.87mm with pad areas 25mm<sup>2</sup>.
- 2. Short duration test pulse used to minimize self-heating effect.
- 3. f = 1kHz.

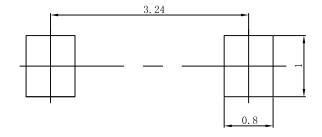
# **Package Outline Dimensions** SOD-123







Symbol	Dimensions	In Millimeters	Dimensions In Inches			
Symbol	Min	Max	Min	Max		
Α	1.050	1.250	0.041	0.049		
A1	0.000	0.100	0.000	0.004		
A2	1.050	1.150	0.041	0.045		
b	0.450	0.650	0.018	0.026		
С	0.080	0.150	0.003	0.006		
D	1.500	1.700	0.059	0.067		
E	2.600	2.800	0.102	0.110		
E1	3.550	3.850	0.140	0.152		
L	0.500	REF	0.020 REF			
L1	0.250	0.450	0.010	0.018		
θ	0°	8°	0°	8°		



#### Note:

- 1. Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.



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